

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 09/827,248  
Filing Date ..... April 4, 2001  
Inventor ..... David R. Hembree  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 2829  
Examiner ..... V. Nguyen  
Attorney's Docket No. ..... MI22-1684  
Title: Methods of Processing Wafers and Methods of Communicating Signals With  
Respect to a Wafer

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

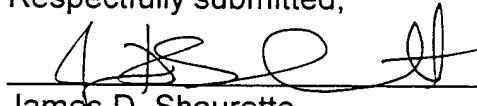
References -- See Attached Form PTO-1449

The attached form PTO-1449 is submitted in compliance with 37 CFR §1.56. No admission is made regarding whether all the submitted references are prior art.

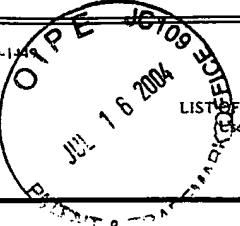
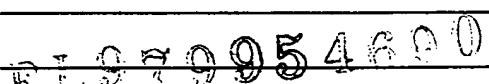
Dated: 2/26/04

Attorney:

Respectfully submitted,

  
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James D. Shaurette  
Reg. No. 39,833

PL479954-290

Form PTO-14  LIST OF ART CITED BY APPLICANT (use several sheets if necessary)				U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-1684		SERIAL NO. 09/827,248	
				APPLICANT Micron Technology, Inc.					
				FILING DATE April 4, 2001		GROUP 2858			
U.S. PATENT DOCUMENTS									
*Examiner Initial		Document Number	Date	Name			Class	Subclass	Filing Date If Appropriate
	AA	4,006,909	2/8/1977	Ollendorf et al.					
	AB								
	AC								
	AD								
	AE								
	AF								
	AG								
	AH								
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)									
	AI								
	AI								
	AK								
	AL								
<u>EXAMINER</u>				<u>DATE CONSIDERED</u>					
<small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>									

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE			ATTY. DOCKET NO. MI22-16804		PRIORITY SERIAL NO. 09/137,629		
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)					APPLICANT David R. Hembree				
					PRIORITY FILING DATE August 21, 1998		PRIORITY GROUP 2858		
U.S. PATENT DOCUMENTS									
*Examiner Initial		Document Number	Date	Name		Class	Subclass	Filing Date If Appropriate	
	AA	4,560,216	12/24/85	Egawa					
	AB	4,754,555	7/5/88	Stillman					
	AC	5,475,317	12/12/95	Smith					
	AD	5,495,667	3/5/96	Farnsworth et al.					
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)									
	AE	S/N: 09/032,184; Filed 2/27/98; Akram et al.; Amendment filed 12/18/00; CPA filed 7/28/00; Amendment filed 3/3/00; Amendment filed 8/23/99; Original Application filed 2/27/98; Pending Claims. <i>4d out</i>							
	AF	Advertisement for Probe Technology: <a href="http://www.idinet.com">www.idinet.com</a> ; Interconnect Devices, Inc., 1 page; 3/6/98							
	AG	Good Things Come In Small BGA/CSP Packages: <a href="http://www.johnstech.com/4/handbook/page9.html">www.johnstech.com/4/handbook/page9.html</a> ; 1 page; 3/5/98							
	AH	Product Description for Double Ended Probes, B1052 Series: <a href="http://www.testprobe.com/products/b1052.html">www.testprobe.com/products/b1052.html</a> ; Rika Densi America, Inc.; 1 page; 2/4/98.							
	AI	Product Description for Test Centers, RM-500 Series Probes. <a href="http://www.testprobe.com/products/rm500.html">www.testprobe.com/products/rm500.html</a> ; Rika Densi America, Inc.; 1 page; 2/4/98.							
	AJ	Product Description for Cost Effective Interconnections for High I/O Products: <a href="http://www.testprobe.com/products/io.html#b1303">www.testprobe.com/products/io.html#b1303</a> ; Rika Densi America, Inc.; 1 page; 2/4/98.							
	AK	Product Description for Ball Grid Probe B1303-C3: <a href="http://www.testprobe.com/products/io.html#b1303">www.testprobe.com/products/io.html#b1303</a> ; Rika Densi America, Inc.; 1 page; 2/4/98.							
	AL	Product Description for Test Socket Contacts: <a href="http://www.johnstech.com/4/handbook/page9.html">www.johnstech.com/4/handbook/page9.html</a> ; 1 page; 3/5/98							
EXAMINER				DATE CONSIDERED					
<p><b>*EXAMINER:</b> Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>									



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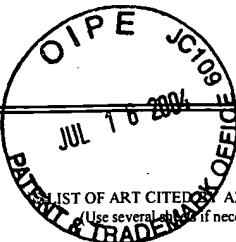
Dated: 7/16/04

Attorney:

Respectfully submitted,

  
James D. Shaurette  
Reg. No. 39,833

EV372455367



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		FILING DATE April 4, 2001		GROUP 2858			
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	5,503,034	4/2/1996	Amano et al.			
	AB	5,964,395	2/1/2000	Glovatsky et al.			
	AC	5,645,764	7/1997	Angelopoulos et al.			
	AD	5,437,189	8/1995	Brown et al.			
	AE						
	AF						
	AG						
	AH						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AI						
	AJ						
	AK						
	AL			EV372455567			
EXAMINER				DATE CONSIDERED			
<small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>							